

Part Number: APHK1608SEC

SUPER BRIGHT ORANGE

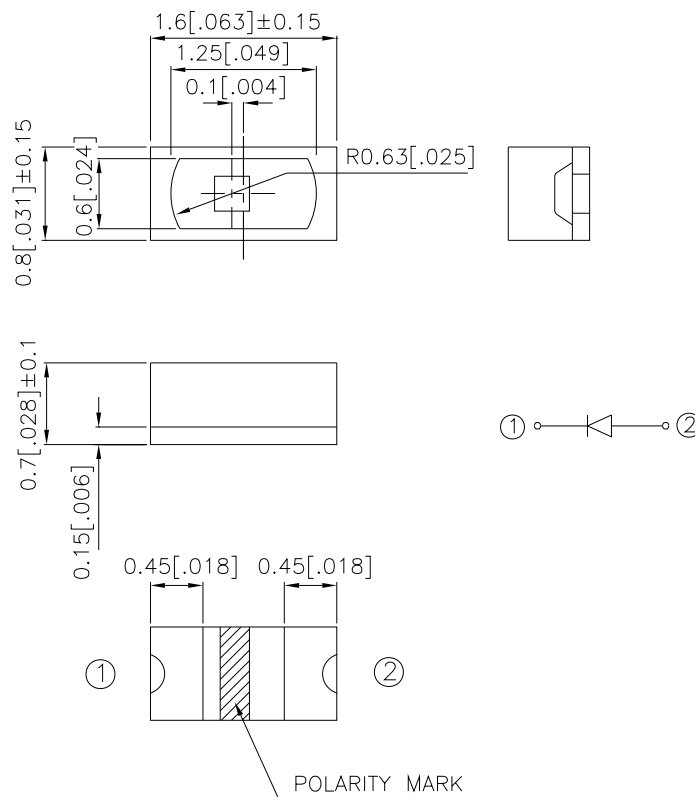
Features

- 1.6mmx0.8mm SMT LED, 0.7mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACK LIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- PACKAGE : 2000PCS / REEL.
- RoHS COMPLIANT.

Description

The Super Bright Orange device is made with DH InGaAlP (on GaAs substrate) light emitting diode chip.

Package Dimensions



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2 θ 1/2
APHK1608SEC	SUPER BRIGHT ORANGE (InGaAlP)	WATER CLEAR	110	280	90°

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Super Bright Orange	610		nm	I _F =20mA
λ_D [1]	Dominant Wavelength	Super Bright Orange	601		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Super Bright Orange	29		nm	I _F =20mA
C	Capacitance	Super Bright Orange	30		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Super Bright Orange	2.0	2.5	V	I _F =20mA
I _R	Reverse Current	Super Bright Orange		10	uA	V _R = 5V

Notes:

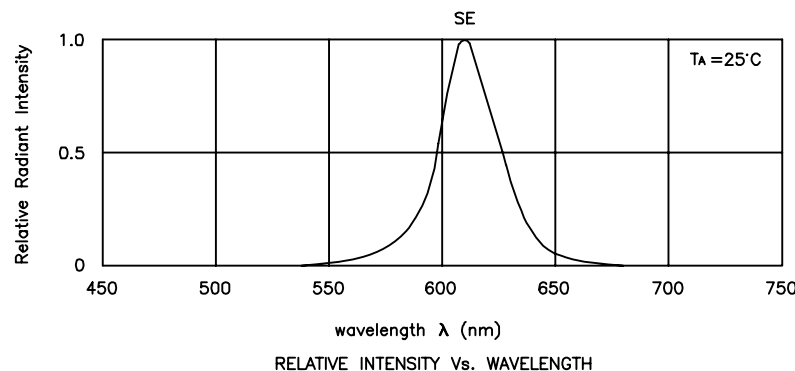
- 1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at T_A=25°C

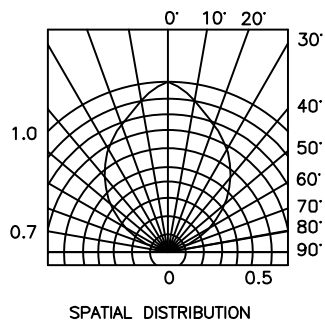
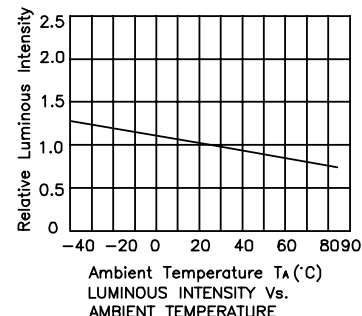
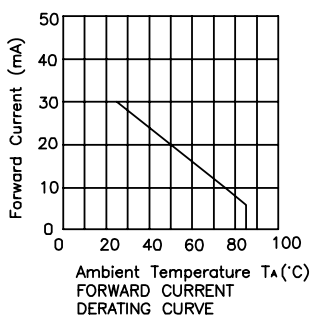
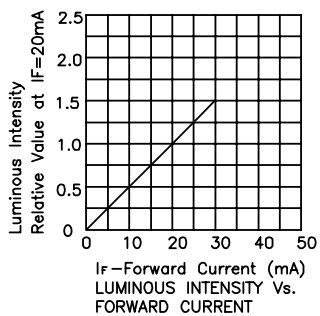
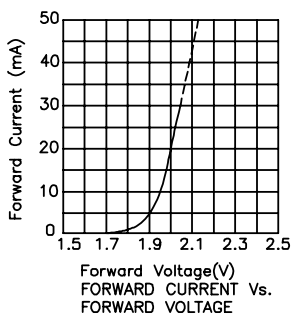
Parameter	Super Bright Orange	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	195	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

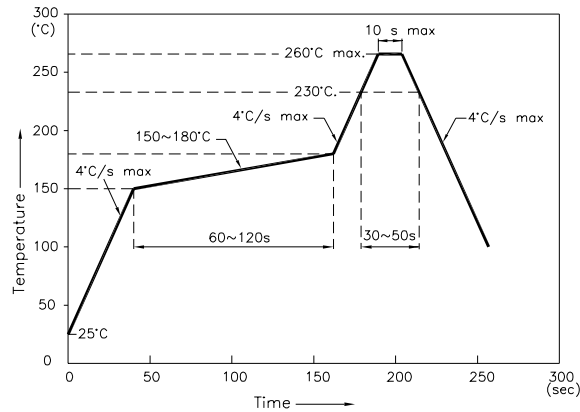


Super Bright Orange APHK1608SEC



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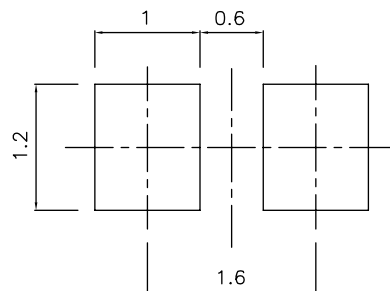
Reflow Soldering Profile For Lead-free SMT Process.



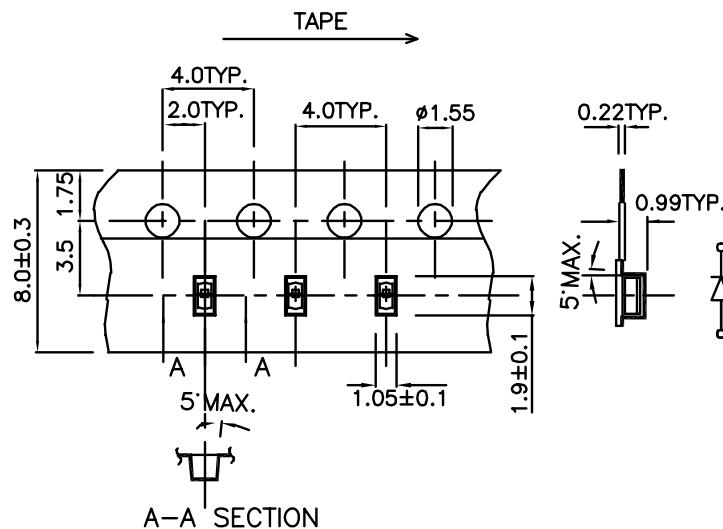
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm ; Tolerance: ± 0.1)

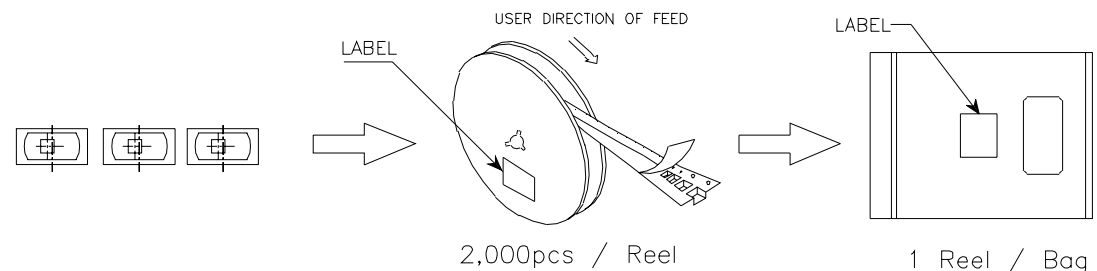


Tape Specifications (Units : mm)

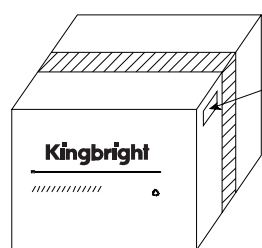


PACKING & LABEL SPECIFICATIONS

APHK1608SEC



60K / 20# BOX



30K / 55# Box

Kingbright	
P/NO: APHK1608XXX	
QTY: 2,000 pcs	Q.C. Q C xx xx.xxxx PASSED
S/N: XXXX	Date
CODE: XXX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	